Kulicke & Soffa to Participate at SMT Hybrid Packaging 2017

SINGAPORE--(BUSINESS WIRE)-- Kulicke & Soffa Industries, Inc. (NASDAQ: KLIC) ("Kulicke & Soffa", "K&S" or the "Company"), announced today that it will be exhibiting at the SMT Hybrid Packaging trade show in Nuremberg, Germany, from May 16 through May 18, 2017.

Kulicke & Soffa will be at the SMT Hybrid Packaging trade show booth 4A-444, showcasing its new packaging solutions.

- Asterion™UW - a new ultrasonic welding solution built on a proven architecture with an expanded bond area, robust pattern recognition capabilities and extremely tight process controls. Ultrasonic welding provides an attractive alternative in high power applications where it has higher current carrying potential than a wire bonded connection. The enlarged area enhances flexibility and reduces line integration costs.
- Hybrid Wafer Feeder - an innovative solution that enables the combination of ultra-high-speed passive and active placement with high-accuracy flip-chip bonding directly from wafer, ideal for high-volume System-in-Package (SiP), flip-chip, die-attach and wafer-level-package manufacturing. Placement accuracy up to 7µm @ 3 sigma, provides a compelling alternative to existing commercial solutions.

Other K&S' solutions such as the IConnPS ProCu PLUS™ high-performance wire bonder, Asterion™ EV (Extended Version) wedge bonder, iFlex H1 multifunction equipment, Quantis™ QFN capillary, as well as FCC™ Plus and Opto™ Plus dicing blades will also be featured at the trade show.

"The new Asterion™UW and Horizontal Wafer Feeder on the Hybrid provides a compelling set of high-reliability solutions serving the automotive, semiconductor and industrial markets," said Chan Pin Chong, Kulicke & Soffa's Senior Vice President, AP-Hybrid, Electronics Assembly, Wedge Bonders, Capillaries and Blades Business Lines.

About Kulicke & Soffa

Kulicke & Soffa (NASDAQ: KLIC) is a leading provider of semiconductor packaging and electronic assembly solutions supporting the global automotive, consumer, communications, computing and industrial segments. As a pioneer in the semiconductor space, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions and organic development, adding advanced packaging, electronics assembly, wedge bonding and a broader range of expendable tools to its core offerings. Combined with its extensive expertise in process technology and focus on development, K&S is well positioned to help customers meet the challenges of packaging and assembling the next-generation of electronic devices. (www.kns.com)

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